# LM10692

# Power Management Unit for SandForce SF3700 SSD Controllers





# **Product Bulletin**

# **High Efficiency Solution Optimized for M.2 Solid State Drives**

#### Overview

The LM10692 from Texas Instruments is a fully integrated power management unit (PMU) designed for SandForce SF3700 controllers. This ultra-small, reliable/flexible, and highly efficient power solution replaces up to six (6) discrete components typically used in these drives. It functions cooperatively with an SF3700 controller to optimize the supply voltage for low power conditions to obtain maximum system efficiency and provide power for NAND flash.

This design scheme delivers longer battery life for portable devices with SSDs. The chip uses I<sup>2</sup>C interface to communicate with the controller to achieve output voltage programmability. Unlike discrete solutions available today, the highly integrated, all-in-one PMU solution from TI delivers a higher performance-to-cost ratio and is specifically designed and optimized with features geared for SSD and flash drives using the SF3700 controller.

#### SandForce SF3700 SSD LM10692 Controller System Control NAND Flash Bypass Mode 2.5A 2.85V / 3.3V 2.5V/200 m/ 1.8V CPE 2.5V ANN Ĭ 10 µF Control Logic and Registers 1.8V/200 mA 1.8V AON 克 10 µF 1.8V CPE 10 µF ± Ž ↓ 10 μF 1.1V AON 1.1V CPE <u>/</u> ፲ <sup>22 μF</sup>

# **Product Highlights**

- Six highly efficient SPIprogrammable buck regulators
- Sleep mode saves power during idle times
- Automatic internal soft-start on each supply limits startup inrush current
- Phase-shifted buck operation reduces input current ripple and capacitor size
- Independent Enable input pins and Power Good output pins for AON (Always-On) and CPE (Core Power) rails

# **Key Specifications**

- ±1% feedback voltage accuracy
- Up to 95% efficient buck regulators
- 2 MHz switching frequency for smaller inductor size
- 36-pin 5 x 5 mm QFN package



## **Features and Benefits**

#### Ideal Power Solution for M.2 SSDs

- Integrated all-in-one power solution saves valuable board space
- 2 MHz switching frequency for smaller inductor size
- Minimum number of external components
- High bandwidth provides fast turn-on without overshoot
- No loop compensation needed
- PFM mode for low load high efficiency operation

# **Features Optimized for SSDs**

- Built-in over-current limit and thermal protection improves safety
- All six supply voltages offer user-programmable options for maximum flexibility (DVS)
- Customizable startup sequencing for greater flexibility
- Bypass mode on Buck1 eliminates inductor for 3.3V M.2 applications
- Easy-to-interface GUI for accelerated design
- Integrated solution leads to higher overall reliability of SSD
- Sleep mode via I<sup>2</sup>C control
- Input power monitor PFAIL
- Fast active discharge
- Low quiescent current conserves battery life

### Visit ti.com/LM10692 for more product information.

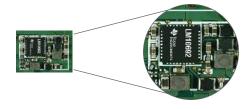
### **Regulator Table**

| Regulator | Programmable V <sub>OUT</sub> (V) | Maximum I <sub>оит</sub> | Description |
|-----------|-----------------------------------|--------------------------|-------------|
| Buck1     | 1.75 to 3.3                       | 2.5A                     | 2.85 CPE    |
| Buck2     | 1.0 to 2.55                       | 200 mA                   | 2.5V AON    |
| Buck3     | 0.8 to 2.35                       | 200 mA                   | 1.8V AON    |
| Buck4     | 0.8 to 2.35                       | 2.5A                     | 1.8V CPE    |
| Buck5     | 0.8 to 1.575                      | 0.8A                     | 1.1V AON    |
| Buck6     | 0.8 to 1.575                      | 2.5A                     | 1.1V CPE    |



LM10692 evaluation board

Complete LM10692 PMU solution size is 13.5 mm x 9.3 mm



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